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Indium Corporation Brings Next-Generation Solder Technologies to SMTA Guadalajara 2026

CLINTON, N.Y., October 1, 2026 – [Indium Corporation](http://www.indium.com), a leading materials manufacturer and supplier to the global electronics, semiconductor, and thermal management markets, will feature a range of innovative, high-reliability solder products at the [SMTA Guadalajara Expo and Tech Forum](#), October 7-8, in Guadalajara, Mexico.

The company will feature the following products:

- [Durafuse® HR](#) is a trusted and proven solder paste alloy technology delivering enhanced thermal cycling performance (-40°C/125°C and -40°C/150°C) and superior voiding control for high-reliability automotive applications. It also offers reduced solder joint cracking and increased shear strength.
- [Durafuse® LT](#) is an award-winning solder paste alloy system that delivers exceptional HiP resistance and high reliability at lower reflow temperatures. It is ideal for assemblies with broad temperature gradients and large BGAs with complex warpage profiles, effectively mitigating HIP defects caused by package warpage.
- [Indalloy® 302](#) is a low-silver solder specifically engineered to balance cost efficiency with long-term reliability. It delivers improved



thermal cycling, wetting, and voiding performance (less than 10%) compared with SAC305 while supporting lower or equivalent reflow temperatures.

- [Indium12.9HF](#) is a no-clean, halogen-free solder paste designed for fine-pitch printing, including 01005 and 008004 components. With excellent HIP resistance and wetting performance, it helps accommodate package warpage while delivering low voiding at BGA, CSP, LGA, and QFN. It also provides high oxidation resistance without graping or solder balling on pads as small as 175 microns in air reflow.
- [Indium9.9TF](#) is a no-clean, halogen-free solder paste for fine-feature printing. It delivers unprecedented stencil transfer efficiency to boost SPI yields, best-in-class voiding performance, and high oxidation resistance—preventing graping on pads as small as 175 microns.

To learn more about Indium Corporation's [Durafuse® Technology](#) and [PCB assembly](#) portfolio, visit indium.com or meet our company experts at SMTA Guadalajara, booth 702.

About Indium Corporation

Indium Corporation® is a premier materials refiner, smelter, manufacturer, and supplier to the global electronics, semiconductor, thin-film, and thermal management markets. Products include solders and fluxes; brazes; thermal interface materials; sputtering targets; indium, gallium, germanium, and tin metals and inorganic compounds; and NanoFoil®. Founded in 1934, the company has global technical support and factories located in China, Germany, India, Malaysia, Mexico, Singapore, South Korea, the United Kingdom, and the U.S.

For more information about Indium Corporation, visit <http://www.indium.com/> or email jhuang@indium.com. You can also follow our experts, From One Engineer To Another® (#FOETA), at www.linkedin.com/company/indium-corporation/.

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